

Glass Wafer with Through Vias
High Quality Microholes in Standard Glasses

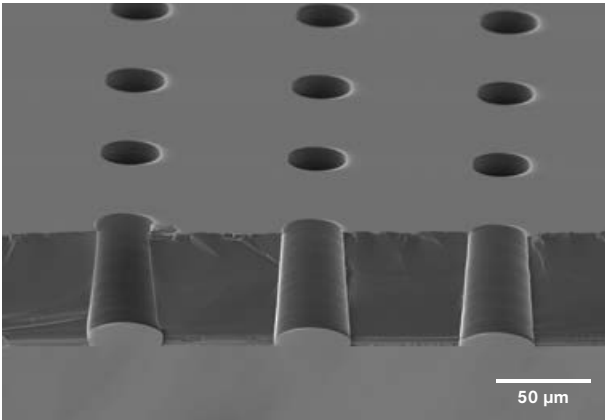


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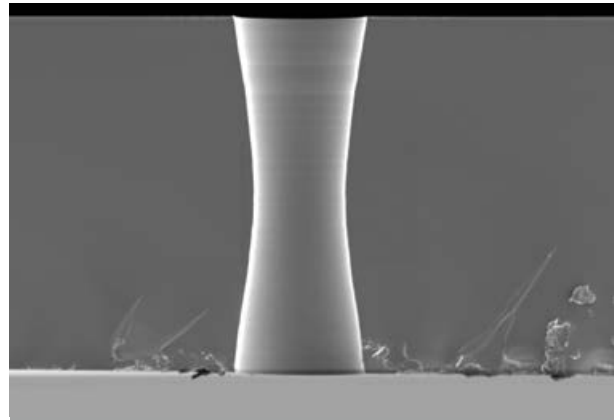
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Glass Wafer with Microholes for TGV

- Glass thickness: <0.9 mm
- Minimum microhole diameter: 10 µm
- Positional accuracy: ± 5 µm
- Taper angle: 1 ° to 7 °
(depending on glass type)
- Chipping: None
- Microcracks: None
- Substrate size and format: All standard wafer sizes up to 450 mm and glass panels up to 510 mm x 510 mm



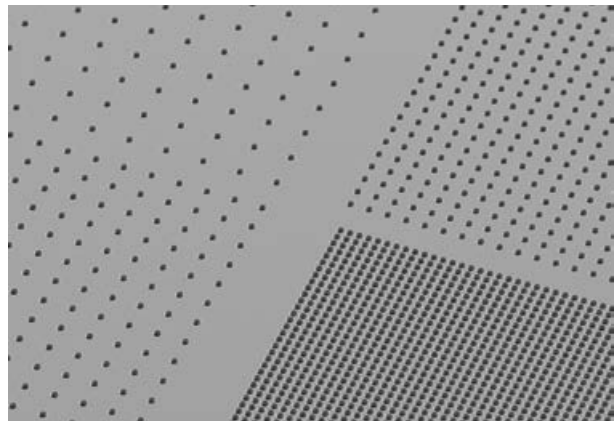
V-shaped Through-Glass Via (TGV)



Hour-glass shaped Through-Glass Via (TGV)



Glass wafer



Detailed view of microholes



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Made in Germany

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